

Martin Hirman

List of Publications by Year in descending order

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38
papers

176
citations

1684188

5
h-index

1588992

8
g-index

38
all docs

38
docs citations

38
times ranked

113
citing authors

#	ARTICLE	IF	CITATIONS
1	Optimization of solder paste quantity considering the properties of solder joints. Soldering and Surface Mount Technology, 2017, 29, 15-22.	1.5	26
2	Project Management during the Industry 4.0 Implementation with Risk Factor Analysis. Procedia Manufacturing, 2019, 38, 1181-1188.	1.9	24
3	Determination of Changes in Process Management within Industry 4.0. Procedia Manufacturing, 2019, 38, 1691-1696.	1.9	18
4	Influence of reflow soldering profiles on creation of IMC at the interface of SnBi/Cu. , 2014, , .		14
5	Relationship of Soldering Profile, Voids Formation and Strength of Soldered Joints. , 2019, , .		10
6	Analysis of Education Requirements for Electronics Manufacturing within Concept Industry 4.0. , 2018, , .		9
7	Adhesion improvement of Thick Printed Copper film on alumina substrates by controlling of oxygen level in furnace. , 2016, , .		8
8	Influence of Sweat on Joint and Sensor Reliability of E-Textiles. Energies, 2022, 15, 506.	3.1	7
9	Alternative technology for SMD components connection by non-conductive adhesive on a flexible substrate. Journal of Materials Science: Materials in Electronics, 2019, 30, 14214-14223.	2.2	6
10	Effect of Washing Cycles on Glued Conductive Joints Used on Stretchable Smart Textile Ribbons. , 2020, , .		6
11	SMD Components Assembly on a Flexible Substrate by Non-Conductive Adhesives. , 2018, , .		5
12	A comparison of the shear strength of conductive adhesives and soldering alloys. , 2015, , .		4
13	The Testing of Brass Solderability for Hybrid Sewing Thread. , 2019, , .		4
14	Design, Fabrication and Risk Assessment of IoT Unit for Products Manufactured in Industry 4.0 Factory. Procedia Manufacturing, 2020, 51, 1178-1183.	1.9	4
15	Comparison of the characteristics of PCB protective coatings. , 2017, , .		3
16	Reliability of Glued Joints on Flexible Substrates During Accelerated Current Ageing. , 2019, , .		3
17	Comparison of QFN Chips Glued by ACA and NCA Adhesives on the Flexible Substrate. , 2019, , .		3
18	Study of low-temperature interconnection techniques for instant assembly of electronics on stretchable e-textile ribbons. Textile Reseach Journal, 0, , 004051752210847.	2.2	3

#	ARTICLE	IF	CITATIONS
19	Nanoparticle based ink printed chip interconnections. , 2017, , .		2
20	Influence of flexible substrate roughness with aerosol jet printed pads on the mechanical shear strength of glued joints. , 2017, , .		2
21	Optimization of Soldering Process to Reduce Contamination and Related Consequences. , 2018, , .		2
22	Electrical Resistance of Solder Joints on Conductive Ribbons. , 2020, , .		2
23	Effects of Accelerated Climatic Aging on Volume and Surface Resistivity of Glass Fiber Reinforced Thermoset Composites. , 2020, , .		2
24	Properties Verification of Improved Lead-free Solder Alloys. , 2021, , .		2
25	Shear Strength of Conductive Adhesive Joints on Rigid and Flexible Substrates Depending on Adhesive Quantity. Journal of Electrical Engineering, 2016, 67, 177-184.	0.7	1
26	Influence of electrically conductive adhesive quantity on insulation distance and shear strength of glued joints. , 2016, , .		1
27	Comparison of copper and silver thick film on alumina substrates properties. , 2017, , .		1
28	Bend Testing of SMD Chip Resistors Glued on Flexible Substrates. , 2019, , .		1
29	Reliability of Glued SMD Components on Smart Textile. , 2020, , .		1
30	Optimization of Contacting Technological Process on Printed Conductive Pattern for Wearable Electronics. , 2020, , .		1
31	Methodologies to Improve Experimental Research Processes in Soldering Technology. Periodica Polytechnica Electrical Engineering and Computer Science, 2016, 60, 237-244.	1.0	1
32	Properties of temperature stable solder pastes. , 2016, , .		0
33	Influence of Increased Voltage on the Characteristics of Printed Circuit Board Protective Coatings. , 2018, , .		0
34	Current trends in the management of diagnostic processes in testing laboratories. , 2018, , .		0
35	Comparison of Conductive Ribbons Reliability during Electrical Current Ageing. , 2020, , .		0
36	Influence of production and operating conditions on properties of acrylic conformal coatings. , 2020, , .		0

#	ARTICLE	IF	CITATIONS
37	Higher Temperature Washing of Electrically Connected SMD Components onto the Textile Ribbons. , 2022, , .		0
38	Alternative interconnection methods for bare die electronic components. , 2022, , .		0